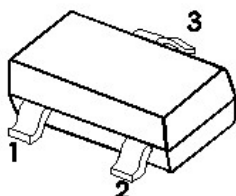


SOT-23

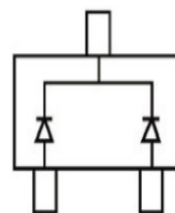
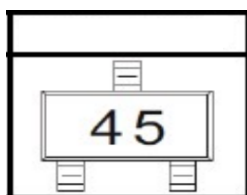


特征 Features

- 大电流承受能力。High Current Capability
- 正向压降低。Low Forward Voltage Drop
- 开关速度快。Extremely Fast Switching Speed

机械数据 Mechanical Data

- 封装: SOT-23 封装 SOT-23 Small Outline Plastic Package
- 环氧树脂 UL 易燃等级 Epoxy UL: 94V-0
- 安装位置: 任意 Mounting Position: Any



MARKING: 45

极限值和温度特性(TA = 25℃ 除非另有规定)

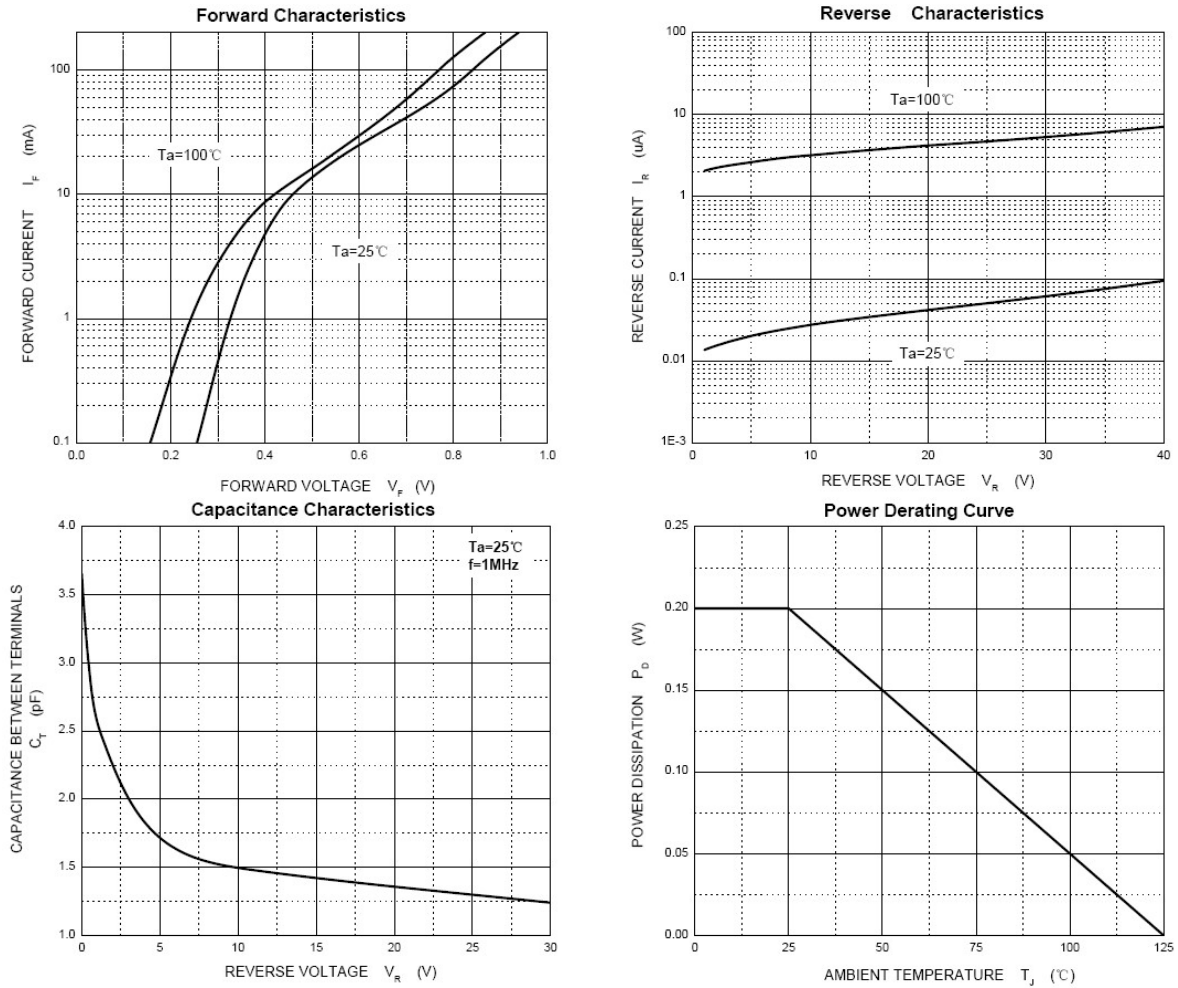
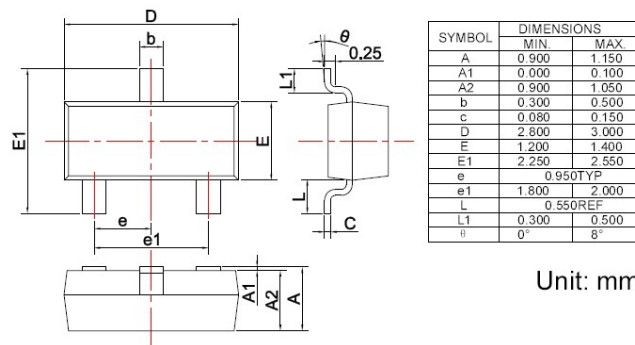
Maximum Ratings & Thermal Characteristics (Ratings at 25℃ ambient temperature unless otherwise specified.)

参数 Parameters	符号 Symbol	界限 Limit	单位 Unit
最大可重复峰值反向电压 Maximum repetitive peak reverse voltage	VRRM	40	V
最大直流阻断电压 Maximum DC blocking voltage	VDC	40	V
最大正向平均整流电流 Maximum average forward rectified current	IFM	200	mA
典型热阻 Typical thermal resistance	RθJA	500	℃/W
功率消耗 Power Dissipation	PD	200	mW
结温 Junction Temperature	Tj	125	℃
存储温度 Storage temperature range	TSTG	-50-+150	℃

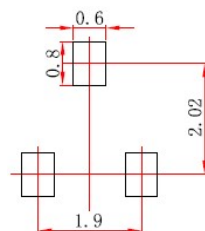
电特性 (TA = 25℃ 除非另有规定)

Electrical Characteristics (Ratings at 25℃ ambient temperature unless otherwise specified).

参数 Parameters	符号 Symbol	测试条件 Test conditions	Min	Typ	Max	单位 Unit
最大正向电压 Maximum forward voltage	VF1	IF = 1mA			380	mV
	VF2	IF = 40mA			1000	
最大反向电压 Maximum reverse breakdown voltage	VR	IR=10uA	40			V
最大反向电流 Maximum reverse current	IR	VR=30V			200	nA
典型结电容 Type junction capacitance	CD	VR = 0V, f = 1MHz			5	pF
反向恢复时间 Reverse Recovery time	trr	IF=IR=10mA Irr=1XIR, RL=100 Ω			5	ns

Typical Characteristics

SOT-23 PACKAGE OUTLINE Plastic surface mounted package


焊盘设计参考 Precautions: PCB Design (Recommended land dimensions for SOT-23 diode. Electrode patterns for PCBs)



Note:
 1. Controlling dimension: In millimeters.
 2. General tolerance: $\pm 0.05\text{mm}$.
 3. The pad layout is for reference purposes only.

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